

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1761ES5-2.8#TRPBF		(Engineering Calculation)		TSOT-23				
(printed on: 7/26/2011 6:02:13 AM)				TOTAL MASS (g):		0.01260123		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000673	1000000	53407.46		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004485	975000	355917.5		
		Iron (Fe)	7439-89-6	0.00011	24000	8729.304		
		Phosphorus (P)	7723-14-0	1.00E-06	300	79.3573		
		Zinc (Zn)	7440-66-6	3.00E-06	700	238.0719		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.004599	1000000	364964.2
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.000635236	1000000	50410.59		
		External Plating Total:				0.000635236	1000000	50410.59
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	8.00E-05	1000000	6348.584		
		Internal Plating Total:				8.00E-05	1000000	6348.584
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000448	750000	35552.07		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0.000149	250000	11824.24		
Die Attach Total:				0.000597	1000000	47376.31		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000775	130000	61501.91		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.004947	830000	392580.6		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0.000209	35000	16585.68		
		Carbon Black (C)	1333-86-4	3.00E-05	5000	2380.719		
Encapsulation Total:				0.005961	1000000	473048.9		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	5.60E-05	1000000	4444.009		
Estimated								
				TOTAL MASS (g):		0.01260123		